

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	138561	(heat near5 (sink spread\$3 dissipat\$3))	US-PGPU B; USPAT; USOCR	OR	ON	2005/05/10 18:50
L2	69869	(substrate wafer) near100 (trench recess groove)	US-PGPU B; USPAT; USOCR	OR	ON	2005/05/10 18:50
L3	4699	1 and 2	US-PGPU B; USPAT; USOCR	OR	ON	2005/05/10 18:08
L4	1743	3 and mask	US-PGPU B; USPAT; USOCR	OR	ON	2005/05/10 18:50
L5	1665	4 and (etch\$3 pattern\$3)	US-PGPU B; USPAT; USOCR	OR	ON	2005/05/10 18:14
L6	67123	(heat near5 (sink spread\$3 dissipat\$3))	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/10 18:50
L7	65867	(substrate wafer) near100 (trench recess groove)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/10 18:50
L8	703	6 and 7	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/10 18:50
L9	31	8 and mask	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/10 18:51